

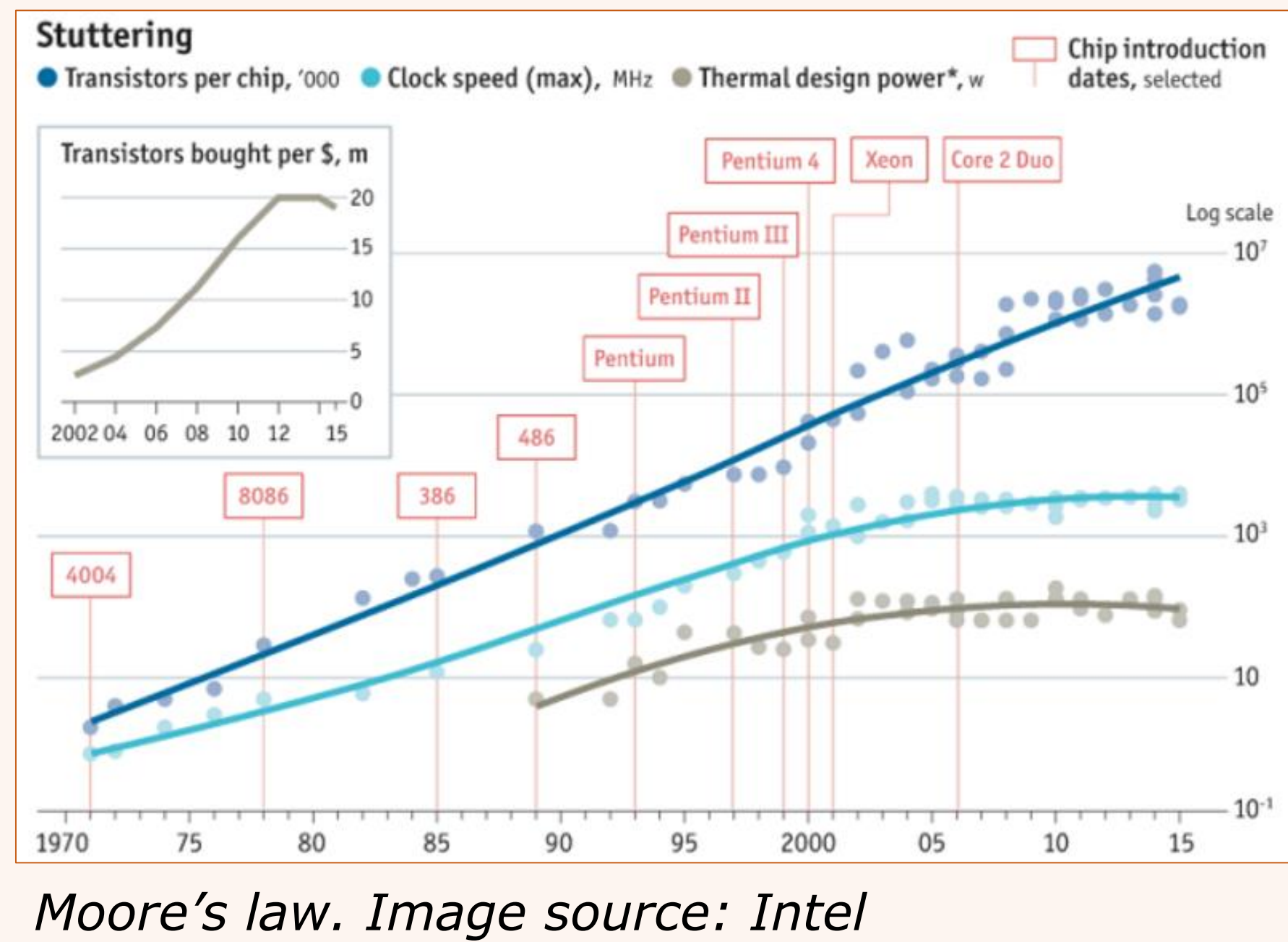
## INTRODUCTION

Semiconductor technology evolution is leading to a reduction of the size of the electronic components from the micro- to the nanoscale. One of the main challenges in this field is understanding the thermal behaviour of these nanostructures. Here we show that the thermal conductivity of nanoscale volumes of silicon samples with various doping and thermal properties of sub-micrometre SiO<sub>x</sub> layers can be reliably characterised via scanning thermal microscopy (SThM).

## MOTIVATION

### ENSURING THE CONTINUITY OF MOORE'S LAW

- High speed electronics
- Spatial shrinking nanometer scale



### CHALLENGE

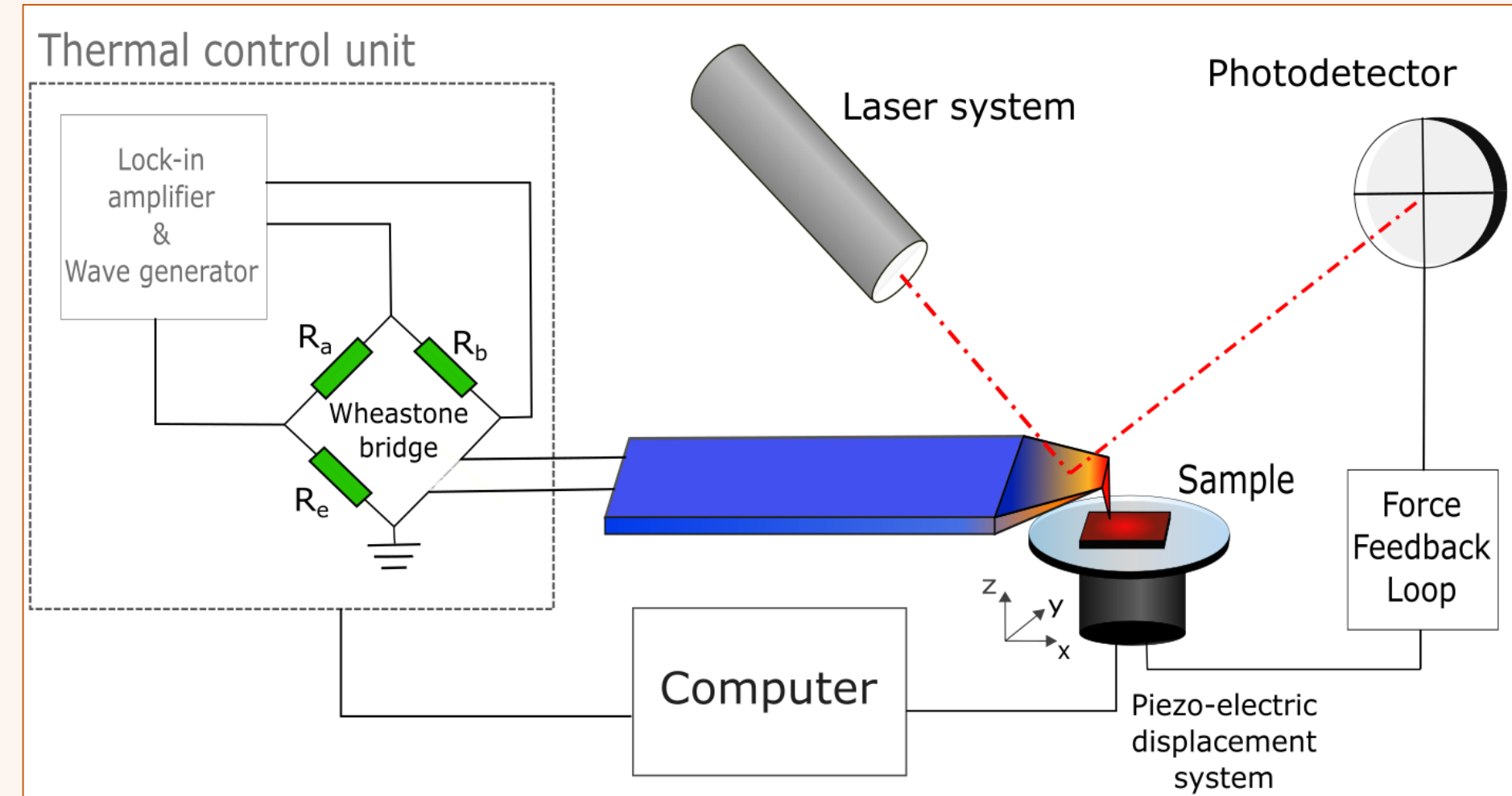
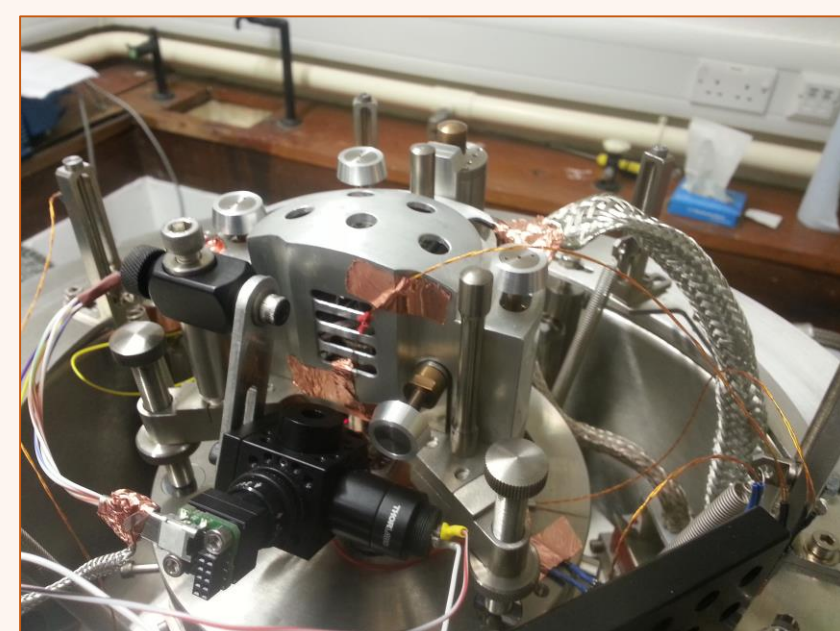
**THERMAL MANAGEMENT AND POWER DISSIPATION**

## SYSTEM

### SCANNING THERMAL MICROSCOPY (SThM)

**MULTIFUNCTIONAL SPM:** Modified NT-MDT Solver

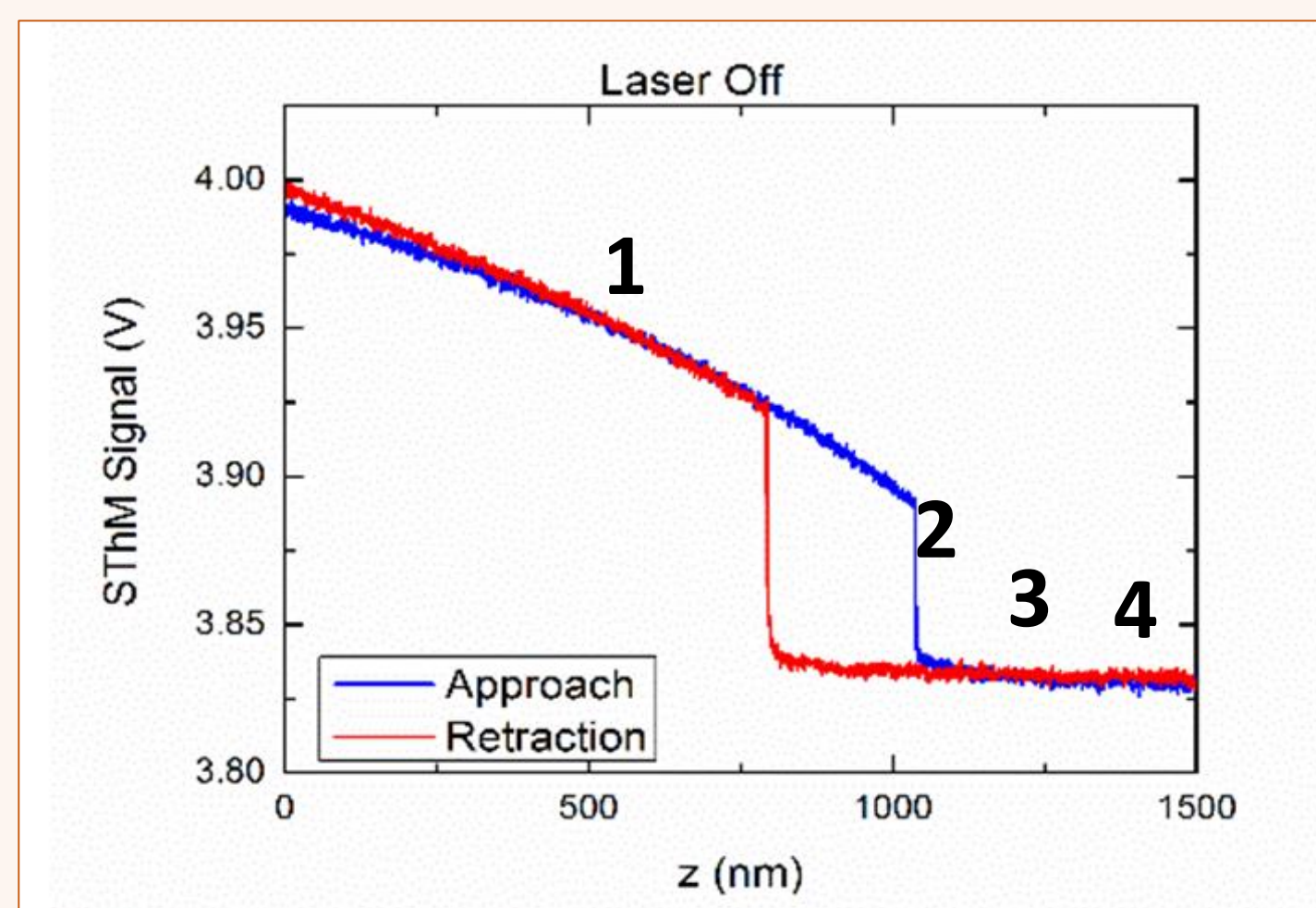
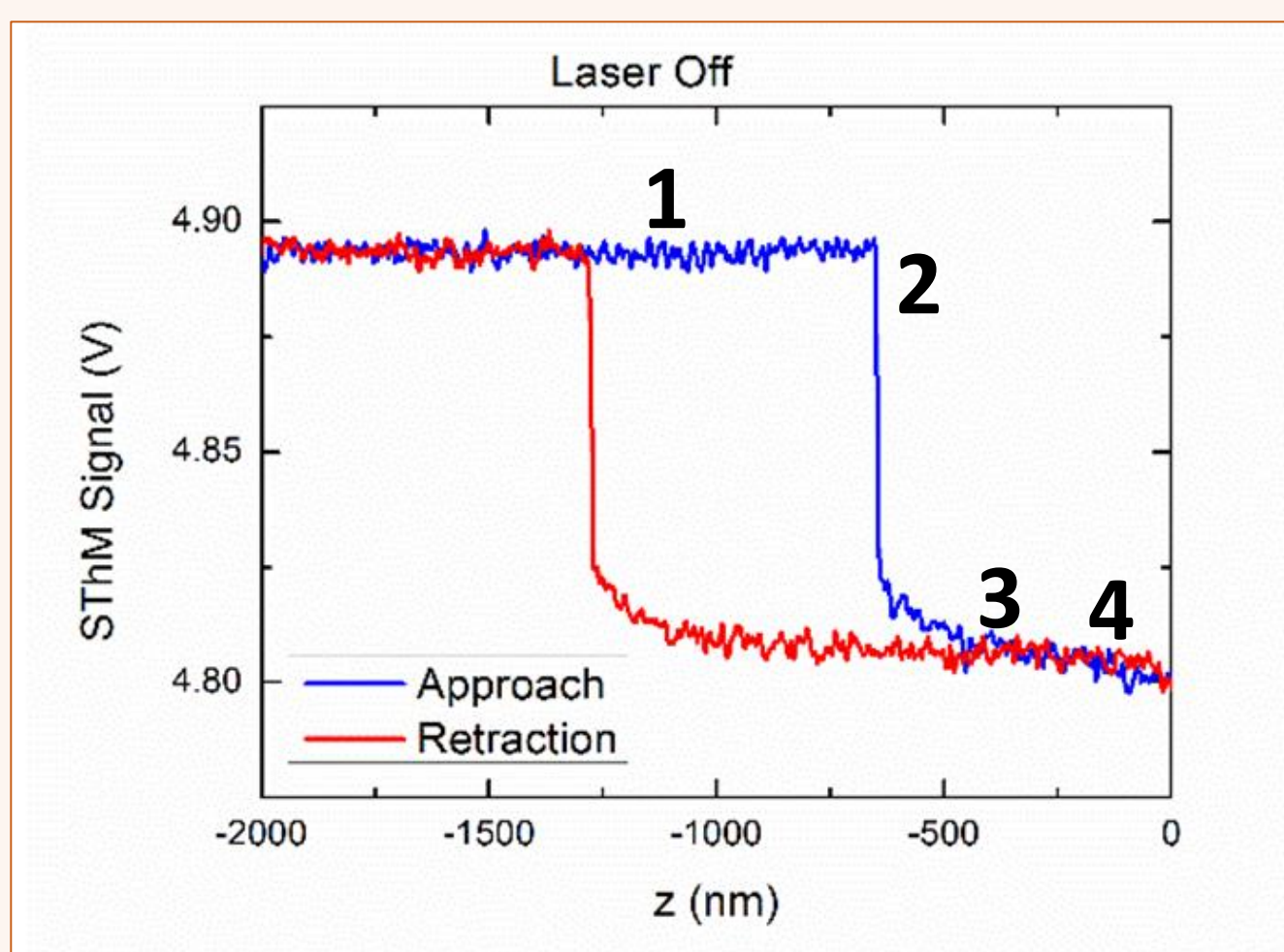
- ☐ High resolution AFM topography
- ☐ Heat transport maps



- Pressure conditions:
  - Ambient: 10<sup>2</sup> torr
  - Vacuum: 10<sup>-7</sup> torr
- Probe:
  - Si<sub>3</sub>N<sub>4</sub> with a Pd coating
  - Doped Si

## METHODOLOGY

**FS-SThM:** Sample – probe approach-retraction curves of SThM thermal signal dV/V response. Increase of thermal conductivity increases dV/V



1.-Approach 2.-Contact 3.-Stabilization 4.-Measurement

## CONCLUSIONS & FUTURE WORK

- SThM allowed to reliably differentiate the thermal conductivity of Si samples with different doping concentration, as well as the thermal conductance of SiO<sub>2</sub> layers of increasing thickness (ranging between 10-100nm). The probed volume in both cases was below 50x50x50 nm<sup>3</sup> with the spatial resolution exceeding 50 nm.
- Using high vacuum conditions and no laser during the measurements allowed to significantly increase measurement precision.
- NEXT STEP: Thermal characterization on the nanoscale of 2D material based heterostructures by using High Vacuum SThM

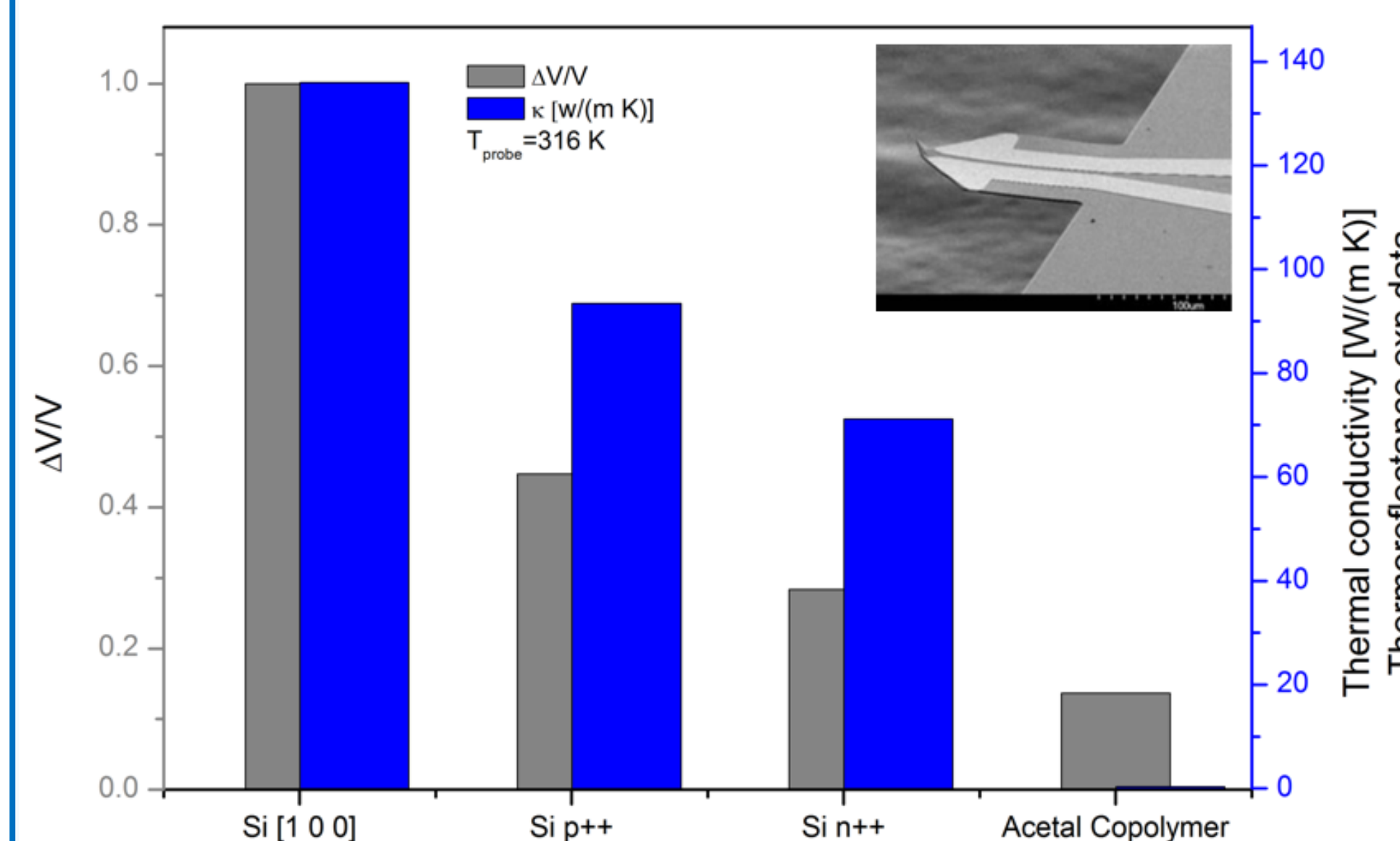
## REFERENCES

[1] Gomès, S. Scanning thermal microscopy: A review. *physica status solidi (a)* **212**, 477-494, doi:10.1002/pssa.201400360 (2015).  
 [2] Tovee, P., Pumarol, M., Zeze, D., Kjoller, K. & Kolosov, O. Nanoscale spatial resolution probes for scanning thermal microscopy of solid state materials. *Journal of Applied Physics* **112**, 114317, doi:10.1063/1.4767923 (2012).

## RESULTS

### THERMAL CHARACTERIZATION OF DIFFERENTLY DOPED SILICON SAMPLES VS A REFERENCE POLYMER SAMPLE

- Probe: Commercial Si<sub>3</sub>N<sub>4</sub> with a Pd thin film resistive temperature sensor (Kelvin Nanotechnology, KNT). Tip radius <100 nm.
- Measurement conditions: 10<sup>2</sup> torr, ~298 K
- Probed volume (~ 50x50x50 nm<sup>3</sup>) is linked with the dimensions of the contact



$$\frac{\Delta V}{V} = \frac{V_{NC} - V_C}{V_{NC}}$$

$$\frac{\Delta V}{V} = \sim \kappa [W/(m \cdot K)]$$

Acknowledgment: Thermoreflectance data was taken by Gil Tossier and Abeer Al Mohtar at Their University, Paris

### THERMAL CHARACTERIZATION OF SiO<sub>2</sub> STEPS

- Sample: SiO<sub>2</sub> steps of increasing thickness, ranging from 10 nm to 1200 nm over a substrate of single crystal Si.
- Probe: Doped silicon (Anasys instruments). Tip radius <30 nm.
- Measurement conditions: 10<sup>-7</sup> torr, ~298 K
- Thermal conductance behaviour: Decreasing tendency from 0-100 nm, probably due to the influence of the underlying Si, and saturation for the layers of thickness > 100 nm.

